

WHAT IS CLAIMED IS:

1. A manufacturing method for electronic component-mounted components, which comprises:

embedding an electronic component into a base;

5 removing the base by carrying out at least one treatment of electrical discharge machining, laser beam machining, ion beam machining and electron beam machining to a machining face of the base, and thereby exposing electrodes of the embedded electronic component; and

10 forming a circuit pattern in contact with the exposed electrodes.

2 The manufacturing method for the electronic component-mounted components according to claim 1, which
15 further comprises:

forming a through hole to penetrate the machining face and a rear face opposite to the machining face while carrying out the treatment to the base, and

while forming the circuit pattern, forming an
20 electric connection between the machining face and the rear face via the through hole by at least one of conductive sputtering, vapor deposition and filling a conductive material.

25 3. The manufacturing method for the electronic

component-mounted components according to claim 1, wherein the electrodes of the electronic component have projecting electrodes, and the exposing operation after the embedding into the base is to expose the projecting electrodes.

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4. The manufacturing method for the electronic component-mounted components according to claim 1, wherein the circuit pattern forming operation forms at least one of a conductor routing, a metal thin film capacitor, a coil and a resistance in contact with the exposed electrodes by any one of plating, ion plating, sputtering and vapor deposition.

5. The manufacturing method for the electronic components-mounted components according to claim 1, wherein the circuit pattern forming operation forms the circuit pattern by printing a solder paste or conductive adhesive on the exposed electrodes, then heating and hardening the solder paste or conductive adhesive.

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6. The manufacturing method for the electronic component-mounted components according to claim 1, wherein embedding the electronic component into the base is carried out to a plurality of electronic components in the same process, and after the circuit pattern is formed, the base

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is cut so as to correspond to respective electronic component-mounted components.

7. The manufacturing method for the electronic component-mounted components according to claim 1, wherein embedding the electronic components into the base is carried out by heat press, the base is a thermoplastic sheet formed of any one of polyvinyl chloride, polycarbonate, acrylonitrile butadiene styrene, thermoplastic polyimide and polyethylene terephthalate and has a thickness of 0.010-2.000mm, a glass transition point of the base is not lower than 333K and not higher than 423K, the electronic component has a thickness smaller than that of the base, electrodes of the electronic component have a height of 0.0005-0.1mm, and the base at the heat press time is set to be a temperature higher by 50K or more than the glass transition point and not higher than 473K.

8. A manufacturing method for electronic component-mounted completed products, which comprises:

manufacturing electronic component-mounted components by a manufacturing method for electronic component-mounted components;

stacking the electronic component-mounted components or a base of the electronic component-mounted

components in a thickness direction of the base after the manufacturing; and

executing a laminating process after the stacking,
the manufacturing method for electronic
5 component-mounted components including:

embedding an electronic component into the base,
removing the base by carrying out at least one
treatment of electrical discharge machining, laser beam
machining, ion beam machining and electron beam machining
10 to a machining face of the base, and thereby exposing
electrodes of the embedded electronic component, and

forming a circuit pattern in contact with the
exposed electrodes.

9. An electronic component-mounted completed product
15 manufactured by a manufacturing method for electronic
component-mounted completed products, the manufacturing
method comprising:

manufacturing electronic component-mounted
components by a manufacturing method for electronic
20 component-mounted components;

stacking the electronic component-mounted
components or a base of the electronic component-mounted
components in a thickness direction of the base after the
manufacturing; and

25 executing a laminating process after the stacking,

the manufacturing method for electronic component-mounted components including:

embedding an electronic component into the base,
removing the base by carrying out at least one
5 treatment of electrical discharge machining, laser beam
machining, ion beam machining and electron beam machining
to a machining face of the base, and thereby exposing
electrodes of the embedded electronic component, and

forming a circuit pattern in contact with the
10 exposed electrodes.